

**Description**

The SX100N08D uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

**General Features**

$V_{DS} = 80V$   $I_D = 100A$

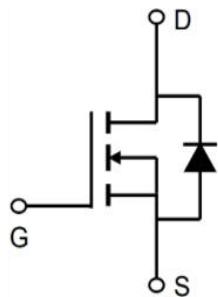
$R_{DS(ON)} < 6.8m\Omega$   $V_{GS}=10V$

**Application**

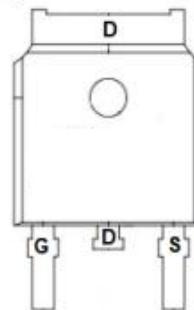
Battery protection

Load switch

Uninterruptible power supply



TO-252-3L

**Absolute Maximum Ratings ( $T_c=25^\circ C$  unless otherwise noted)**

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	80	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D @ T_c=25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^{1,6}$	100	A
$I_D @ T_c=100^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^{1,6}$	60	A
$IDM$	Pulsed Drain Current <sup>2</sup>	400	A
$EAS$	Single Pulse Avalanche Energy <sup>3</sup>	506	mJ
$P_D @ T_c=25^\circ C$	Total Power Dissipation <sup>4</sup>	158	W
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C
$R_{\theta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>	92	°C/W
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	1.22	°C/W

**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$ , $I_D=250\mu\text{A}$	80	92	---	V
RDS(ON)	Static Drain-Source On-Resistance <sup>2</sup>	$V_{GS}=10\text{V}$ , $I_D=50\text{A}$	---	5.5	6.8	$\text{m}\Omega$
VGS(th)	Gate Threshold Voltage	$V_{GS}=V_{DS}$ , $I_D=250\mu\text{A}$	2.0	3.0	4.0	V
IDSS	Drain-Source Leakage Current	$V_{DS}=80\text{V}$ , $V_{GS}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	1	$\text{uA}$
		$V_{DS}=80\text{V}$ , $V_{GS}=0\text{V}$ , $T_J=55^\circ\text{C}$	---	---	5	
IGSS	Gate-Source Leakage Current	$V_{GS}=\pm 20\text{V}$ , $V_{DS}=0\text{V}$	---	---	$\pm 100$	nA
gfs	Forward Transconductance	$V_{DS}=5\text{V}$ , $I_D=20\text{A}$	---	75	---	S
R <sub>g</sub>	Gate Resistance	$V_{DS}=0\text{V}$ , $V_{GS}=0\text{V}$ , $f=1\text{MHz}$	---	2.0	---	$\Omega$
Qg	Total Gate Charge (10V)	$V_{DS}=40\text{V}$ , $V_{GS}=10\text{V}$ , $I_D=20\text{A}$	---	56.6	---	nC
Qgs	Gate-Source Charge		---	21.4	---	
Qgd	Gate-Drain Charge		---	12.5	---	
Td(on)	Turn-On Delay Time	$V_{DD}=40\text{V}$ , $V_{GS}=10\text{V}$ , $R_G=3\Omega$ , $I_D=20\text{A}$	---	17.3	---	ns
Tr	Rise Time		---	33	---	
Td(off)	Turn-Off Delay Time		---	38.9	---	
Tf	Fall Time		---	18.1	---	
Ciss	Input Capacitance	$V_{DS}=40\text{V}$ , $V_{GS}=0\text{V}$ , $f=1\text{MHz}$	---	3475	---	pF
Coss	Output Capacitance		---	770	---	
Crss	Reverse Transfer Capacitance		---	25	---	
IS	Continuous Source Current <sup>1,5</sup>	$V_G=V_D=0\text{V}$ , Force Current	---	---	100	A
VSD	Diode Forward Voltage <sup>2</sup>	$V_{GS}=0\text{V}$ , $I_S=A$ , $T_J=25^\circ\text{C}$	---	0.9	1.3	V
trr	Reverse Recovery Time	$I_F=20\text{A}$ , $dI/dt=100\text{A}/\mu\text{s}$ , $T_J=25^\circ\text{C}$	---	68	---	nS
Qrr	Reverse Recovery Charge		---	66	---	nC

**Note :**

- 1、The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2、The data tested by pulsed , pulse width .The EAS data shows Max. rating .
- 3、The test cond  $\leq 300\mu\text{s}$  duty cycle  $\leq 2\%$ , duty cycle ition is  $V_{DD}=64\text{V}$ ,  $V_{GS}=10\text{V}$ ,  $L=0.1\text{mH}$ ,  $I_{AS}=40\text{A}$
- 4、The power dissipation is limited by  $175^\circ\text{C}$ Junction temperature
- 5、The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.

## Typical Characteristics

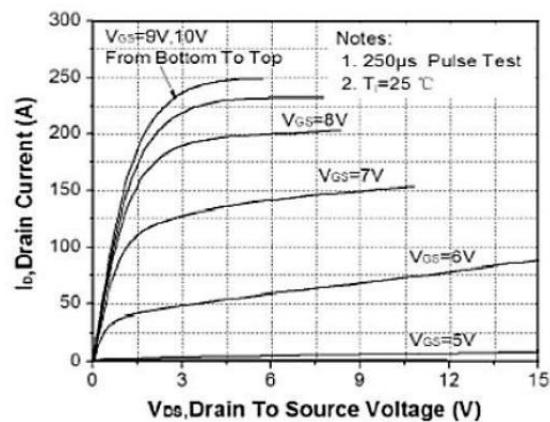


Figure 1. Typ. Output Characteristics ( $T_j=25^\circ\text{C}$ )

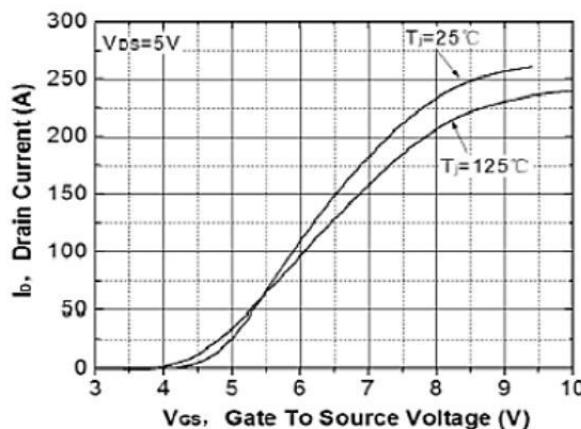


Figure 2. Transfer Characteristics

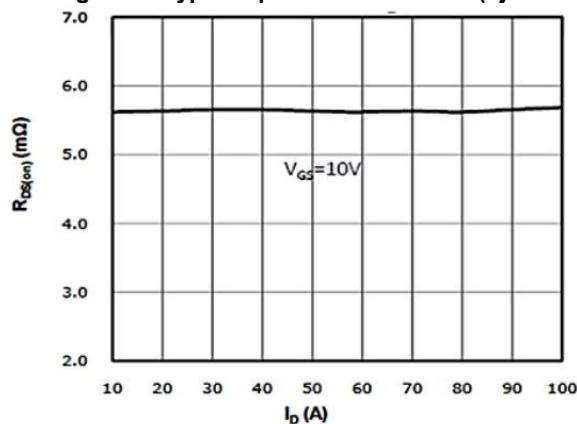


Figure 3. On-Resistance vs. Drain Current and Gate Voltage Figure

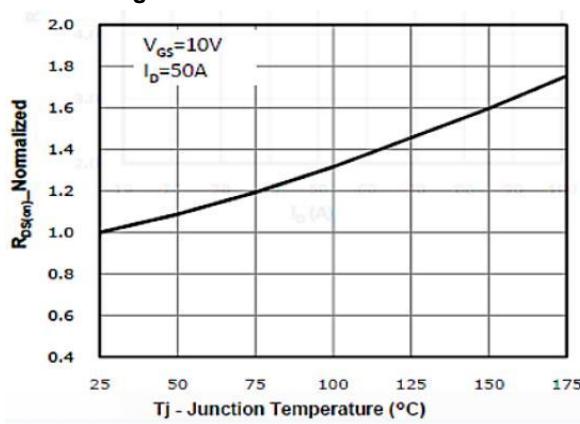


Figure 4. On-Resistance vs. Junction Temperature

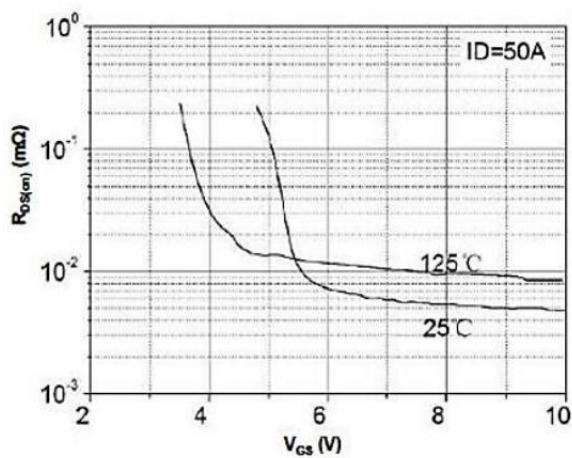


Figure 5. On-Resistance vs. Gate-Source Voltage

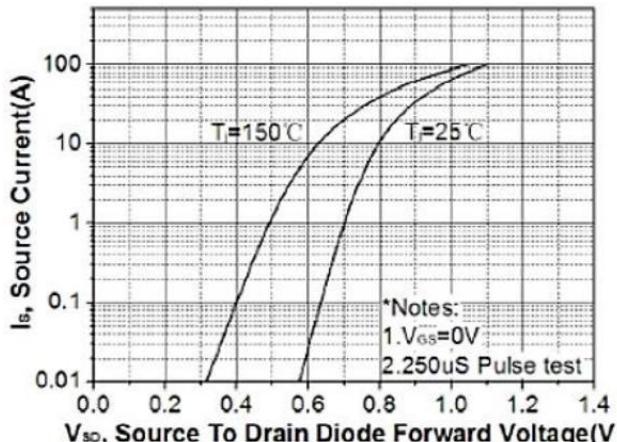


Figure 6 . Body-Diode Characteristics

## Typical Characteristics

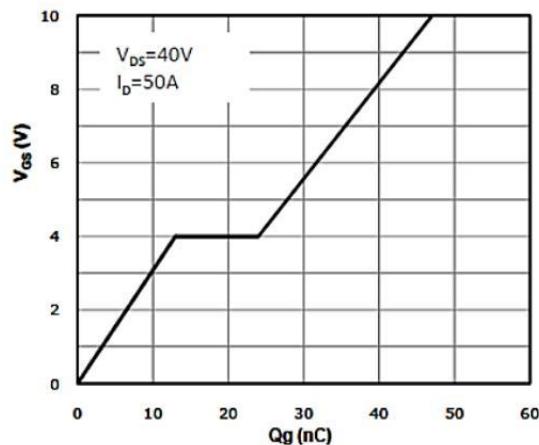


Figure 7. Gate-Charge Characteristics

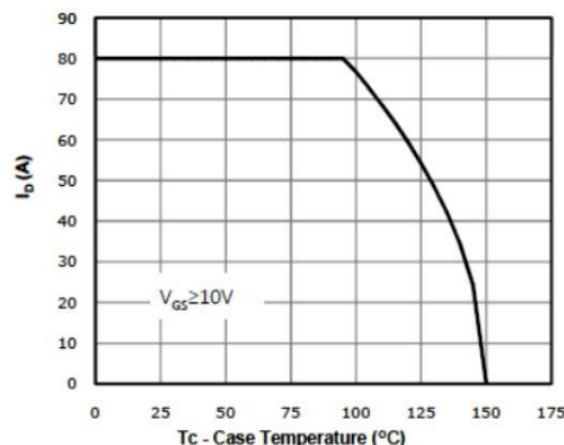


Figure 8. Drain Current Derating

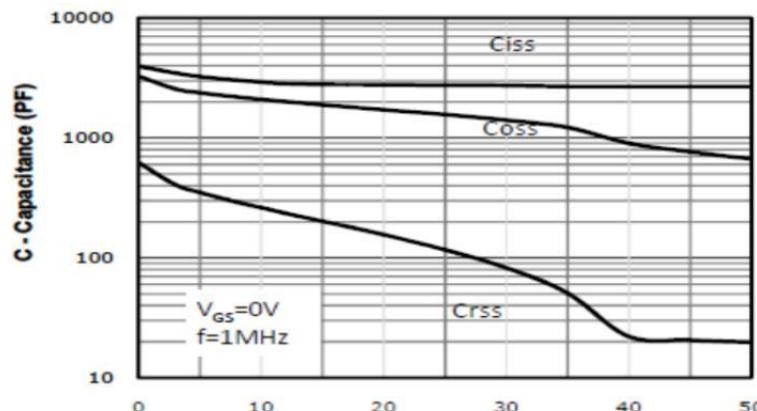


Figure 9: Normalized Maximum Transient Thermal Impedance

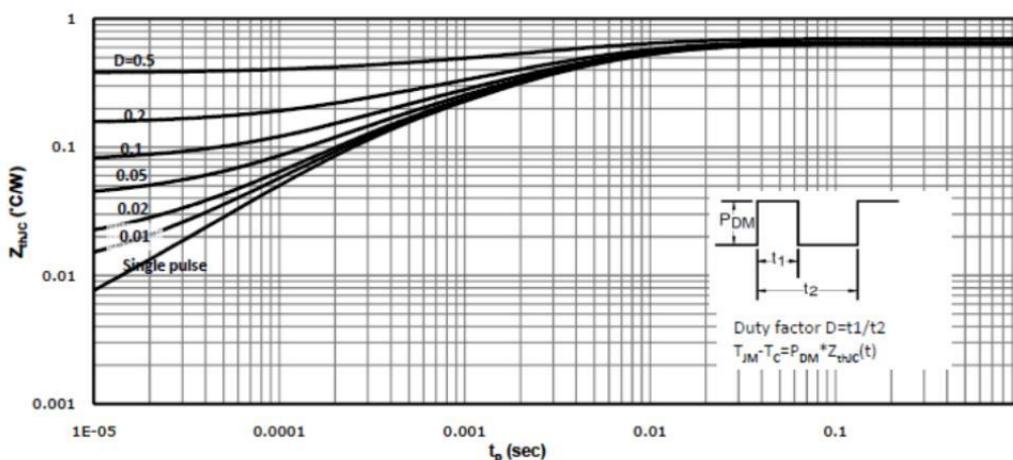
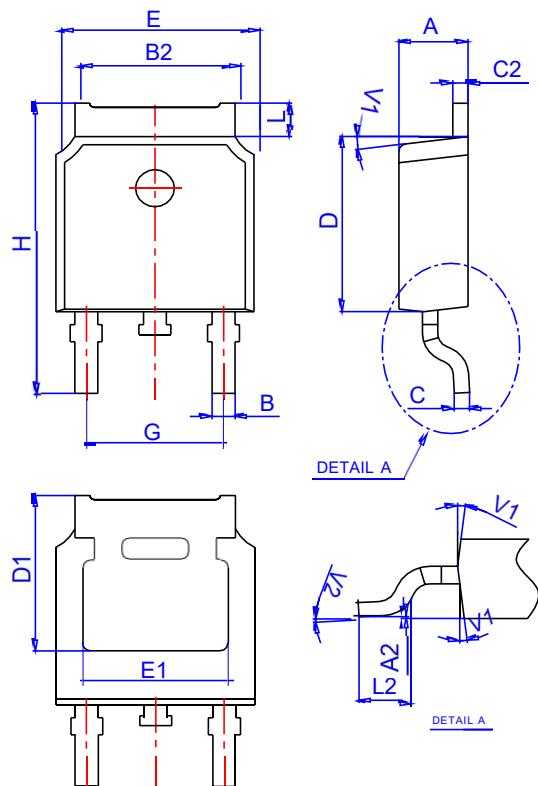


Figure 10. Capacitance Characteristics

## Package Mechanical Data : TO-252-3L



Ref.	Dimensions					
	Millimeters			Inches		
Min.	Typ.	Max.	Min.	Typ.	Max.	
A	2.10		2.50	0.083		0.098
A2	0		0.10	0		0.004
B	0.66		0.86	0.026		0.034
B2	5.18		5.48	0.202		0.216
C	0.40		0.60	0.016		0.024
C2	0.44		0.58	0.017		0.023
D	5.90		6.30	0.232		0.248
D1	5.30REF			0.209REF		
E	6.40		6.80	0.252		0.268
E1	4.63			0.182		
G	4.47		4.67	0.176		0.184
H	9.50		10.70	0.374		0.421
L	1.09		1.21	0.043		0.048
L2	1.35		1.65	0.053		0.065
V1		7°			7°	
V2	0°		6°	0°		6°

### Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
TAPING	TO-252-3L		2500